

HIGH-SPEED 32K x 8 DUAL-PORT STATIC RAM

FEATURES:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed access
 - Military: 25/35/55ns (max.)
 - Commercial: 20/25/35/55ns (max.)
- Low-power operation
 - IDT7007S

Active: 750mW (typ.) Standby: 5mW (typ.)

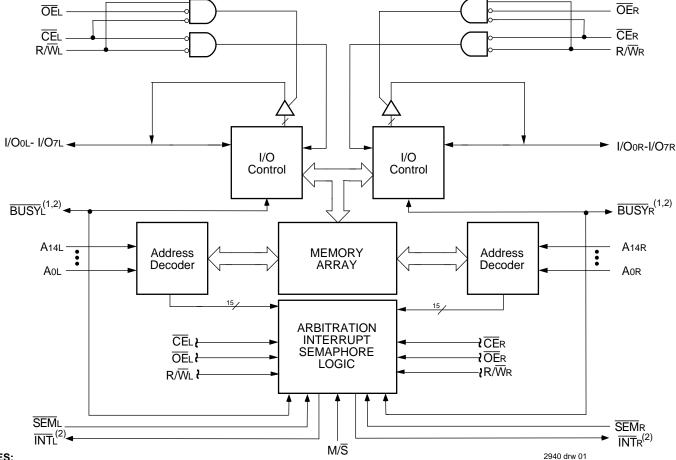
— IDT7007L

Active: 750mW (typ.) Standby: 1mW (typ.)

 IDT7007 easily expands data bus width to 16 bits or more using the Master/Slave select when cascading more than one device

- M/S = H for BUSY output flag on Master, M/S = L for BUSY input on Slave
- · Busy and Interrupt Flags
- On-chip port arbitration logic
- Full on-chip hardware support of semaphore signaling between ports
- Fully asynchronous operation from either port
- Devices are capable of withstanding greater than 2001V electrostatic discharge
- TTL-compatible, single 5V (±10%) power supply
- Available in 68-pin PGA, 68-pin PLCC, and a 80-pin TOFP
- Industrial temperature range (–40°C to +85°C) is available, tested to military electrical specifications

FUNCTIONAL BLOCK DIAGRAM



NOTES:

- 1. (MASTER): BUSY is output; (SLAVE): BUSY is input.
- 2. BUSY and INT outputs are non-tri-stated push-pull.

The IDT logo is a registered trademark of Integrated Device Technology, Inc.

DSC-2940/4

DESCRIPTION:

The IDT7007 is a high-speed 32K x 8 Dual-Port Static RAM. The IDT7007 is designed to be used as a stand-alone 256K-bit Dual-Port RAM or as a combination MASTER/SLAVE Dual-Port RAM for 16-bit-or-more word systems. Using the IDT MASTER/SLAVE Dual-Port RAM approach in 16-bit or wider memory system applications results in full-speed, error-free operation without the need for additional discrete logic.

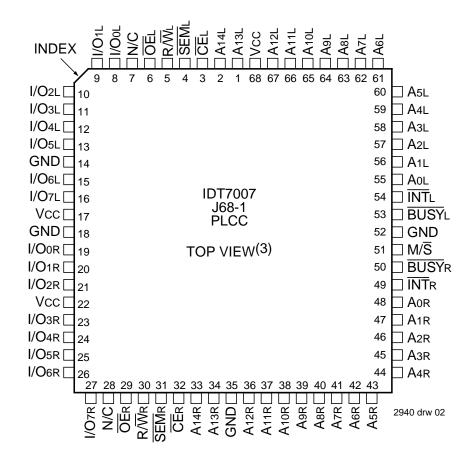
This device provides two independent ports with separate control, address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in

memory. An automatic power down feature controlled by $\overline{\text{CE}}$ permits the on-chip circuitry of each port to enter a very low standby power mode.

Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 750mW of power.

The IDT7007 is packaged in a 68-pin pin PGA, a 68-pin PLCC, and a 80-pin TQFP (thin plastic quad flatpack). Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B, making it ideally suited to military temperature applications demanding the highest level of performance and reliability.

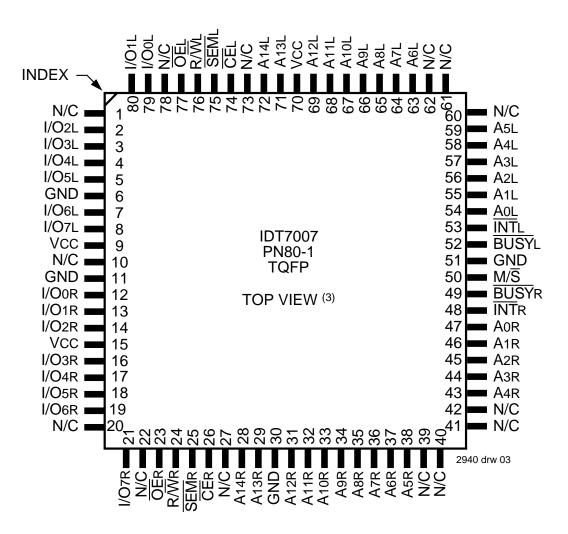
PIN CONFIGURATIONS(1,2)



NOTES:

- 1. All Vcc pins must be connected to power supply.
- 2. All GND pins must be connected to power supply.
- 3. This text does not indicate orientation of the actual part marking.

PIN CONFIGURATIONS (CONT'D.) (1,2)



NOTES:

- 1. All Vcc pins must be connected to power supply.
- 2. All GND pins must be connected to power supply.
- 3. This text does not indicate orientation of the actual part marking.

PIN CONFIGURATIONS (CONT'D.) (1,2)

11		51 A5L	50 A4L	48 A2L	46 A0L	44 BUSYL	42 M/S	40 INTR	38 A1R	36 A3R	
10	53 A7L	52 A6L	49 A3L	47 A1L	45 ĪNTL	43 GND	41 BUSYR	39 A0R	37 A2R	35 A4R	34 A5R
09	55 A9L	54 A8L								32 A7R	33 A6R
08	57 A11L	56 A10L								30 A9R	31 A8R
07	59 VCC	58 A12L				IDT70 G68-				28 A11R	29 A10R
06	61 A14L	60 A13L				B-PIN	PGA			26 GND	27 A12R
05	63 SEML	62 CEL			10	op Vie	= VV (3)			24 A14R	25 A13R
04	65 OEL	64 R/WL								22 SEMR	23 CER
03	67 I/O0L	66 N/C								20 OER	21 R/WR
02	68 I/O1L	1 I/O2L	3 I/O4L	5 GND	7 I/O7L	9 GND	11 I/O1R	13 VCC	15 I/O4R	18 I/O7R	19 N/C
01		2 I/O3L	4 I/O5L	6 I/O6L	8 VCC	10 I/O0R	12 I/O2R	14 I/O3R	16 I/O5R	17 I/O6R	
INIDE	A	В	С	D	Е	F	G	Н	J	K	L
INDE	X										2940 drw 0

NOTES:

- 1. All Vcc pins must be connected to power supply.
- 2. All GND pins must be connected to ground supply.
- 3. This text does not indicate orientation of the actual part marking.

PIN NAMES

Left Port	Right Port	Names
CEL	CER	Chip Enable
R/WL	R/W̄R	Read/Write Enable
ŌĒL	ŌĒR	Output Enable
A0L – A14L	A0R – A14R	Address
I/O0L — I/O7L	I/Oor – I/O7R	Data Input/Output
SEML	<u>SEM</u> R	Semaphore Enable
ĪNTL	ĪNTr	Interrupt Flag
BUSYL	BUSYR	Busy Flag
N	I/S	Master or Slave Select
V	CC	Power
G	ND	Ground

2940 tbl 01

TRUTH TABLE: NON-CONTENTION READ/WRITE CONTROL

	Inp	uts ⁽¹⁾		Outputs	
CE	R/W	ŌĒ	SEM	I/O ₀₋₇	Mode
Н	Х	Х	Н	High-Z	Deselected: Power-Down
L	L	Х	Н	DATAIN	Write to Memory
L	Н	L	Н	DATAout	Read Memory
Х	Х	Н	Х	High-Z	Outputs Disabled

NOTE:

2940 tbl 02

1. A0L — A14L \neq A0R — A14R.

TRUTH TABLE: SEMAPHORE READ/WRITE CONTROL(1)

	Inp	uts		Outputs	
CE	R/W	ŌĒ	SEM	I/O ₀₋₇	Mode
Н	Н	L	L	DATAOUT	Read Semaphore Flag Data Out (I/Oo-I/O7)
Н	1	Х	L	DATAIN	Write I/O ₀ into Semaphore Flag
L	Х	Х	L	_	Not Allowed

NOTE:

2940 tbl 03

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Commercial	Military	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
Та	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
Тѕтс	Storage Temperature	-55 to +125	-65 to +150	°C
lout	DC Output Current	50	50	mA

NOTES:

2940 tbl (

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vcc + 0.5V for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vcc + 0.5V.

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Ambient Temperature	GND	Vcc
Military	−55°C to +125°C	0V	5.0V ± 10%
Commercial	0°C to +70°C	0V	5.0V ± 10%

2940 tbl 05

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	٧
GND	Supply Voltage	0	0	0	V
ViH	Input High Voltage	2.2	ı	6.0 ⁽²⁾	V
VIL	Input Low Voltage	-0.5 ⁽¹⁾	_	0.8	V

NOTES:

2940 tbl 06

- 1. $VIL \ge -1.5V$ for pulse width less than 10ns.
- 2. VTERM must not exceed Vcc + 0.5V.

CAPACITANCE⁽¹⁾

 $(TA = +25^{\circ}C, f = 1.0MHz)TQFP ONLY$

Symbol	Parameter	Conditions ⁽¹⁾	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	9	pF
Соит	Output Capacitance	Vout = 3dV	10	pF

NOTES:

2940 tbl 07

- This parameter is determined by device characterization but is not production tested.
- 2. 3dV represents the interpolated capacitance when the input and output signals switch from 0V to 3V or from 3V to 0V.

^{1.} There are eight semaphore flags written to via I/Oo and read from all I/O's (I/Oo-I/O7). These eight semaphores are addressed by Ao - A2.

DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE (Vcc = $5.0V \pm 10\%$)

			IDT7	007S	IDT70	007L	
Symbol	Parameter	Test Conditions	Min.	Max.	Min.	Max.	Unit
ILI	Input Leakage Current ⁽¹⁾	Vcc = 5.5V, VIN = 0V to Vcc	_	10	_	5	μΑ
ILO	Output Leakage Current	$\overline{\text{CE}}$ = ViH, Vout = 0V to Vcc	_	10	_	5	μΑ
Vol	Output Low Voltage	IOL = 4mA	-	0.4	_	0.4	V
Vон	Output High Voltage	IOH = - 4mA	2.4		2.4	_	V

NOTE:

2940 tbl 08

DC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽¹⁾ (Vcc = $5.0V \pm 10\%$)

		Test			Com'l	7X20 . Only		7X25	
Symbol	Parameter	Condition	Version		Typ. ⁽²⁾	Max.	Тур. ⁽²⁾	Max.	Unit
Icc	Dynamic Operating Current	CE = VIL, Outputs Open SEM = VIH	MIL.	S L	_		170 170	345 305	mA
	(Both Ports Active)	$f = fMAX^{(3)}$	COM'L.	S L	180 180	315 275	170 170	305 265	
ISB1	Standby Current (Both Ports — TTL	$\overline{CER} = \overline{CEL} = VIH$ $\overline{SEMR} = \overline{SEML} = VIH$	MIL.	S L	_		25 25	100 80	mA
	Level Inputs)	$f = fMAX^{(3)}$	COM'L.	S L	30 30	85 60	25 25	85 60	
ISB2	Standby Current	\overline{CE} "A" = VIL and \overline{CE} "B" = VIH ⁽⁵⁾	MIL.	S	_		105	230	mΑ
	(One Port — TTL	Active Port Outputs Open,		L	_	_	105	200	
	Level Inputs)	$f = fMAX^{(3)}$	COM'L.	S	115	210	105	200	
		$\overline{\text{SEM}}_{R} = \overline{\text{SEM}}_{L} = V_{IH}$		L	115	180	105	170	
ISB3	Full Standby Current (Both Ports — All	Both Ports CEL and CER ≥ VCC - 0.2V	MIL.	S L		1 1	1.0 0.2	30 10	mA
	CMOS Level Inputs)	$VIN \ge VCC - 0.2V$ or $VIN \le 0.2V$, $f = 0^{(4)}$ $\overline{SEMR} = \overline{SEML} \ge VCC - 0.2V$	COM'L.	S L	1.0 0.2	15 5	1.0 0.2	15 5	
ISB4	Full Standby Current (One Port — All	$\overline{\text{CE}}$ "A" $\leq 0.2\text{V}$ and $\overline{\text{CE}}$ "B" $\geq \text{VCC} - 0.2\text{V}^{(5)}$	MIL.	S L			100 100	200 175	mA
	CMOS Level Inputs)	$\overline{SEMR} = \overline{SEML} \ge VCC - 0.2V$ $VIN \ge VCC - 0.2V \text{ or } VIN \le 0.2V$ $Active Port Outputs Open$	COM'L.	S L	110 110	185 160	100 100	275 230	
		$f = fMAX^{(3)}$							

NOTES:

2940 tbl 09

- 1. "X" in part numbers indicates power rating (S or L).
- 2. Vcc = 5V, TA = +25°C, and are not production tested. Iccdc = 120mA (Typ.)
- 3. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1 / tRc, and using "AC Test Conditions" of input levels of GND to 3V.
- 4. f = 0 means no address or control lines change.
- 5. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

^{1.} At Vcc ≤ 2.0V, input leakages are undefined.

DC ELECTRICAL CHARACTERISTICS OVER THE **OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽¹⁾(Cont'd.)** (Vcc = 5.0V ± 10%)

		Test			7007	′X35	7007	'X55	
Symbol	Parameter	Condition	Vers	sion	Typ. ⁽²⁾	Max.	Typ. ⁽²⁾	Max.	Unit
Icc	Dynamic Operating Current	CE = VIL, Outputs Open SEM = VIH	MIL.	S L	_	335 295	150 150	310 270	mA
	(Both Ports Active)	$f = fMAX^{(3)}$	COM'L.	S L	160 160	295 255	150 150	270 230	
ISB1	Standby Current (Both Ports — TTL	CEL = CER = VIH SEMR = SEML = VIH	MIL.	S L	_	100 80	13 13	100 80	mA
	Level Inputs)	$f = fMAX^{(3)}$	COM'L.	S L	20 20	85 60	13 13	85 60	
ISB2	Standby Current	\overline{CE} "A" = VIL and \overline{CE} "B" = VIH ⁽⁵⁾	MIL.	S	_	215	85	195	mA
	(One Port — TTL	Active Port Outputs Open,		L	_	185	85	165	
	Level Inputs)	$f = fMAX^{(3)}$	COM'L.	S	95	185	85	165	1
		SEMR = SEML = VIH		L	95	155	85	135	
ISB3	Full Standby Current (Both Ports — All	Both Ports CEL and CER ≥ Vcc - 0.2V	MIL.	S L	_	30 10	1.0 0.2	30 10	mA
	CMOS Level Inputs)	$VIN \ge VCC - 0.2V$ or $VIN \le 0.2V$, $f = 0^{(4)}$ $\overline{SEMR} = \overline{SEML} \ge VCC - 0.2V$	COM'L.	S L	1.0 0.2	15 5	1.0 0.2	15 5	-
ISB4	Full Standby Current (One Port — All CMOS Level Inputs)	$\overline{\text{CE}}$ "A" \leq 0.2V and $\overline{\text{CE}}$ "B" \geq VCC - 0.2V $^{(5)}\overline{\text{CE}}$ R \geq VCC - 0.2V $\overline{\text{SEM}}$ R $=$ $\overline{\text{SEML}}$ \geq VCC - 0.2V	MIL.	S L	_	190 165	80 80	165 140	mA
	. ,	VIN ≥ VCC - 0.2V or	COM'L.	S	90	160	80	135	1
		VIN \leq 0.2V Active Port Outputs Open, $f = f_{MAX}^{(3)}$		L	90	135	80	110	

1. "X" in part numbers indicates power rating (S or L). 2. Vcc = 5V, TA = +25°C, and are not production tested. Iccdc = 120mA (Typ.)

At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1/ tRC, and using "AC Test Conditions" of input levels of GND to 3V.
 f = 0 means no address or control lines change.
 Port "A" may be either left or right port. Port "B" is the opposite from port "A".

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1 and 2
	2940 thl 11

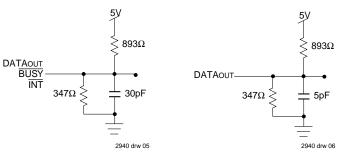


Figure 1. AC Output Load

Figure 2. Output Test Load (for tLz, tHz, twz, tow) * Including scope and jig.

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽⁴⁾

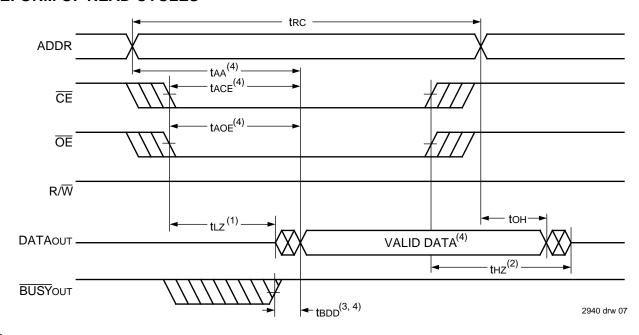
		IDT7007X20 Com'l. Only		IDT70	07X25	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CY	CLE					
tRC	Read Cycle Time	20	_	25	_	ns
taa	Address Access Time	_	20	_	25	ns
tACE	Chip Enable Access Time ⁽³⁾	_	20	_	25	ns
tAOE	Output Enable Access Time	_	12	_	13	ns
tон	Output Hold from Address Change	3	_	3	_	ns
tLZ	Output Low-Z Time ^(1, 2)	3	_	3	_	ns
tHZ	Output High-Z Time ^(1, 2)	_	12	_	15	ns
tPU	Chip Enable to Power Up Time ⁽²⁾	0	_	0	_	ns
tPD	Chip Disable to Power Down Time ⁽²⁾	_	20	_	25	ns
tsop	Semaphore Flag Update Pulse (OE or SEM)	10	_	12	_	ns
tsaa	Semaphore Address Access Time		20	_	25	ns

		IDT70	07X35	IDT70	07X55	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CY	CLE					
trc	Read Cycle Time	35	_	55	_	ns
tAA	Address Access Time	_	35	1	55	ns
tACE	Chip Enable Access Time ⁽³⁾	_	35	1	55	ns
tAOE	Output Enable Access Time	_	20		30	ns
tон	Output Hold from Address Change	3		3	_	ns
tLZ	Output Low-Z Time ^(1, 2)	3	_	3	_	ns
tHZ	Output High-Z Time ^(1, 2)	_	15	1	25	ns
tpU	Chip Enable to Power Up Time ⁽²⁾	0		0		ns
tPD	Chip Disable to Power Down Time ⁽²⁾	_	35	1	50	ns
tsop	Semaphore Flag Update Pulse (OE or SEM)	15	_	15	_	ns
tsaa	Semaphore Address Access Time	_	35	_	55	ns

2940 tbl 12

- 1. Transition is measured ±200mV from Low or High-impedance voltage with Output Test Load (Figure 2).
- This parameter is guaranteed by device characterization, but is not production tested.
 To access RAM, CE = VIL and SEM = VIH. To access semaphore, CE = VIH and SEM = VIL.
- 4. "X" in part numbers indicates power rating (S or L).

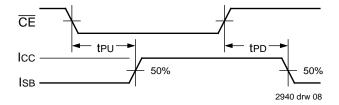
WAVEFORM OF READ CYCLES(5)



NOTES

- 1. Timing depends on which signal is asserted last, $\overline{\text{OE}}$ or $\overline{\text{CE}}$.
- 2. Timing depends on which signal is de-asserted first $\overline{\text{CE}}$ or $\overline{\text{OE}}$.
- 3. tedd delay is required only in cases where the opposite port is completing a write operation to the same address location. For simultaneous read operations BUSY has no relation to valid output data.
- 4. Start of valid data depends on which timing becomes effective last tAOE, tACE, tAA, or tBDD.
- 5. $\overline{SEM} = VIH.$

TIMING OF POWER-UP POWER-DOWN



AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE⁽⁵⁾

			7007X20 n'l. Only	IDT70		
Symbol	Parameter	Min.	Max	Min.	Max.	Unit
WRITE C	YCLE					
twc	Write Cycle Time	20	_	25	_	ns
tew	Chip Enable to End-of-Write ⁽³⁾	15	_	20	_	ns
taw	Address Valid to End-of-Write	15	_	20	_	ns
tas	Address Set-up Time ⁽³⁾	0	_	0	_	ns
twp	Write Pulse Width	15	_	20	_	ns
twr	Write Recovery Time	0	_	0	_	ns
tow	Data Valid to End-of-Write	15	_	15	_	ns
tHZ	Output High-Z Time ^(1, 2)		12	_	15	ns
tDH	Data Hold Time ⁽⁴⁾	0	_	0	_	ns
twz	Write Enable to Output in High-Z ^(1, 2)		12	_	15	ns
tow	Output Active from End-of-Write ^(1, 2, 4)	0	_	0	_	ns
tswrd	SEM Flag Write to Read Time	5	_	5	_	ns
tsps	SEM Flag Contention Window	5	_	5	_	ns

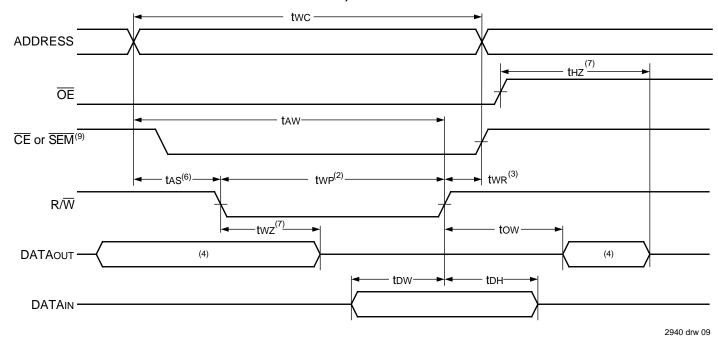
		IDT	7007X35	IDT70		
Symbol	Parameter	Min.	Max	Min.	Max.	Unit
WRITE C'	YCLE					
twc	Write Cycle Time	35	_	55	_	ns
tew	Chip Enable to End-of-Write ⁽³⁾	30	_	45	_	ns
taw	Address Valid to End-of-Write	30	_	45	_	ns
tas	Address Set-up Time ⁽³⁾	0	_	0	_	ns
twp	Write Pulse Width	25	_	40	_	ns
twr	Write Recovery Time	0	_	0	_	ns
tow	Data Valid to End-of-Write	15	_	30	_	ns
tHZ	Output High-Z Time ^(1, 2)	_	15	_	25	ns
tDH	Data Hold Time ⁽⁴⁾	0	_	0	_	ns
twz	Write Enable to Output in High-Z ^(1, 2)	_	15	_	25	ns
tow	Output Active from End-of-Write ^(1, 2, 4)	0	_	0		ns
tswrd	SEM Flag Write to Read Time	5	_	5	_	ns
tsps	SEM Flag Contention Window	5	_	5	_	ns

NOTES

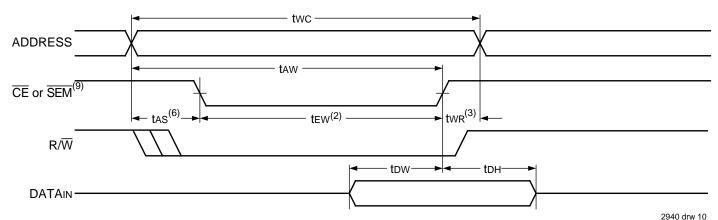
2940 tbl 13

- 1. Transition is measured ±200mV from Low or High-impedance voltage with Output Test Load (Figure 2).
- 2. This parameter is guaranteed by device characterization, but is not production tested.
- 3. To access RAM, $\overrightarrow{CE} = V_{IL}$ and $\overrightarrow{SEM} = V_{IH}$. To access semaphore, $\overrightarrow{CE} = V_{IH}$ and $\overrightarrow{SEM} = V_{IL}$. Either condition must be valid for the entire tew time.
- 4. The specification for toH must be met by the device supplying write data to the RAM under all operating conditions. Although toH and tow values will vary over voltage and temperature, the actual toH will always be smaller than the actual tow.
- 5. "X" in part numbers indicates power rating (S or L).

TIMING WAVEFORM OF WRITE CYCLE NO. 1, R/W CONTROLLED TIMING(1,5,8)



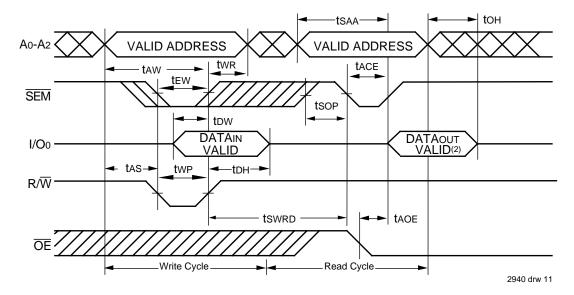
TIMING WAVEFORM OF WRITE CYCLE NO. 2, $\overline{\text{CE}}$ CONTROLLED TIMING^(1,5)



NOTES

- 1. R/\overline{W} or \overline{CE} must be HIGH during all address transitions.
- 2. A write occurs during the overlap (tew or twp) of a LOW \overline{CE} and a LOW R/\overline{W} for memory array writing cycle.
- 3. twn is measured from the earlier of $\overline{\text{CE}}$ or R/\overline{W} (or $\overline{\text{SEM}}$ or R/\overline{W}) going HIGH to the end of write cycle.
- 4. During this period, the I/O pins are in the output state and input signals must not be applied.
- 5. If the CE or SEM LOW transition occurs simultaneously with or after the R/W LOW transition, the outputs remain in the High-impedance state.
- 6. Timing depends on which enable signal is asserted last, $\overline{\text{CE}}$ or R/\overline{W} .
- 7. This parameter is guaranteed by device characterization, but is not production tested. Transition is measured ± 200mV from steady state with the Output Test Load (Figure 2).
- 8. If \overline{OE} is LOW during R/W controlled write cycle, the write pulse width must be the larger of twp or (twz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If \overline{OE} is HIGH during an R/W controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified twp.
- 9. To access RAM, $\overline{CE} = VIL$ and $\overline{SEM} = VIH$. To access semaphore, $\overline{CE} = VIH$ and $\overline{SEM} = VIL$. tew must be met for either condition.

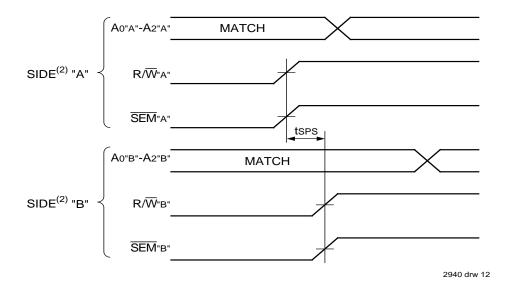
TIMING WAVEFORM OF SEMAPHORE READ AFTER WRITE TIMING, EITHER SIDE(1)



NOTES:

- 1. $\overline{CE} = VIH$ for the duration of the above timing (both write and read cycle).
- 2. "DATAou⊤ VALID" represents all I/O's (I/O₀-I/Ō) equal to the semaphore value.

TIMING WAVEFORM OF SEMAPHORE WRITE CONTENTION(1,3,4)



NOTES:

- 1. Dor = Dol = VIL, $\overline{CER} = \overline{CEL} = VIH$.
- 2. All timing is the same for left and right ports. Port "A" may be either left or right port. "B" is the opposite from port "A".
- 3. This parameter is measured from R/W"A" or SEM"A" going HIGH to R/W"B" or SEM"B" going HIGH.
- 4. If tsps is not satisfied there is no guarantee which side will be granted the semaphore flag.

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽⁶⁾

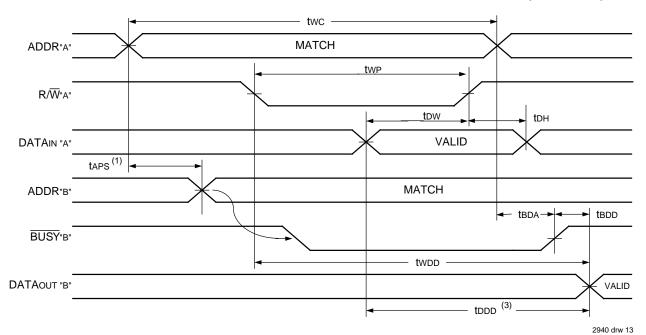
		-	07X20 I. Only	IDT70		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
BUSY TIM	MING (M/S = ViH)					_
tbaa	BUSY Access Time from Address Match	_	20	_	20	ns
tBDA	BUSY Disable Time from Address Not Matched	_	20	_	20	ns
tBAC	BUSY Access Time from Chip Enable Low	_	20	_	20	ns
tBDC	BUSY Disable Time from Chip Enable High	_	17	_	17	ns
taps	Arbitration Priority Set-up Time ⁽²⁾	5	_	5	_	ns
tBDD	BUSY Disable to Valid Data ⁽³⁾	_	30	_	30	ns
twн	Write Hold After BUSY ⁽⁵⁾	15	_	17	_	ns
BUSY TIM	IING (M/S = VIL)	•		•		
twB	BUSY Input to Write ⁽⁴⁾	0	_	0	_	ns
twH	Write Hold After BUSY ⁽⁵⁾	15	_	17	_	ns
PORT-TO	-PORT DELAY TIMING	•				
twdd	Write Pulse to Data Delay ⁽¹⁾	_	45	_	50	ns
tDDD	Write Data Valid to Read Data Delay ⁽¹⁾	_	30	_	35	ns

		IDT70	007X35	IDT70		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
BUSY TIM	/ING (M/S = ViH)					
tbaa	BUSY Access Time from Address Match	_	20	_	45	ns
tBDA	BUSY Disable Time from Address Not Matched	_	20	_	40	ns
tBAC	BUSY Access Time from Chip Enable Low	_	20	_	40	ns
tBDC	BUSY Disable Time from Chip Enable High	_	20	_	35	ns
taps	Arbitration Priority Set-up Time ⁽²⁾	5	1	5		ns
tBDD	BUSY Disable to Valid Data ⁽³⁾	_	35	-	40	ns
twH	Write Hold After BUSY ⁽⁵⁾	25	_	25	_	ns
BUSY TIM	∕IING (M/S̄ = Vı∟)					
twB	BUSY Input to Write ⁽⁴⁾	0	_	0	_	ns
twH	Write Hold After BUSY ⁽⁵⁾	25	_	25	_	ns
PORT-TO	-PORT DELAY TIMING	•			•	
twdd	Write Pulse to Data Delay ⁽¹⁾	_	60	_	80	ns
tDDD	Write Data Valid to Read Data Delay ⁽¹⁾	_	45	_	65	ns

1. Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Write with Port-to-Port Read and BUSY (M/S = VIH)".

- 2. To ensure that the earlier of the two ports wins.
- 3. tbdd is a calculated parameter and is the greater of 0, twdd twp (actual), or tddd tdw (actual).
- To ensure that the write cycle is inhibited on port "B" during contention on port "A".
 To ensure that a write cycle is completed on port "B" after contention on port "A".
- 6. "X" in part numbers indicates power rating (S or L).

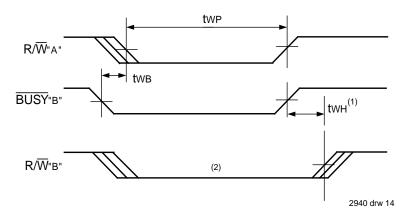
TIMING WAVEFORM OF WRITE WITH PORT-TO-PORT READ AND \overline{BUSY} (M/ \overline{S} = VIH) $^{(2,4,5)}$



NOTES:

- 1. To ensure that the earlier of the two ports wins. taps is ignored for $M/\overline{S} = V_{IL}$ (SLAVE).
- 2. $\overline{CE}L = \overline{CE}R = VIL$
- 3. $\overline{OE} = V_{IL}$ for the reading port.
- 4. If M/S = VIL (slave), BUSY is an input. Then for this example BUSY A" = VIH and BUSY B" input is shown above.
- 5. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

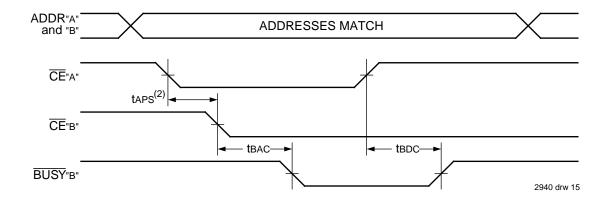
TIMING WAVEFORM OF WRITE WITH BUSY $(M/\overline{S} = Vil)^{(3)}$



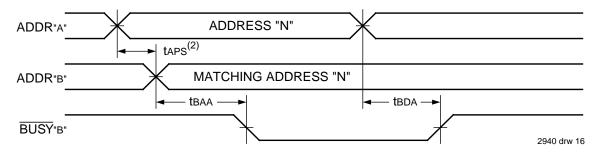
NOTES:

- 1. twn must be met for both $\overline{\text{BUSY}}$ input (SLAVE) and output (MASTER).
- 2. \overline{BUSY} is asserted on port "B" blocking R/ \overline{W} "B", until \overline{BUSY} "B" goes High.
- 3. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

WAVEFORM OF BUSY ARBITRATION CONTROLLED BY \overline{CE} TIMING (M/ \overline{S} = Vih)(1)



WAVEFORM OF BUSY ARBITRATION CYCLE CONTROLLED BY ADDRESS MATCH TIMING (M/ \overline{S} = Vih)⁽¹⁾



NOTES:

- 1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
- 2. If tAPS is not satisfied, the busy signal will be asserted on one side or another but there is no guarantee on which side busy will be asserted.

AC ELECTRICAL CHARACTERISTICS OVER THE OPERATING TEMPERATURE AND SUPPLY VOLTAGE RANGE⁽¹⁾

		IDT700 Com'l.	-	IDT700		
Symbol	Parameter	Min.	Max.	Min	Max.	Unit
INTERRU	PT TIMING					
tas	Address Set-up Time	0	_	0	_	ns
twr	Write Recovery Time	0	_	0	_	ns
tins	Interrupt Set Time	_	20	_	20	ns
tinr	Interrupt Reset Time	_	20	_	20	ns

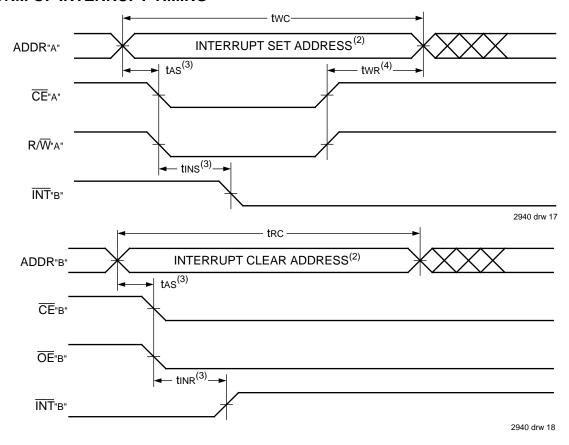
		IDT700	7X35	IDT700		
Symbol	Parameter	Min.	Max.	Min	Max.	Unit
INTERRU	PT TIMING					
tas	Address Set-up Time	0	_	0	_	ns
twr	Write Recovery Time	0	_	0	_	ns
tins	Interrupt Set Time	_	25	_	40	ns
tinr	Interrupt Reset Time	_	25	_	40	ns

NOTE

1. "X" in part numbers indicates power rating (S or L).

2739 tbl 15

WAVEFORM OF INTERRUPT TIMING(1)



NOTES:

- 1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
- 2. See Interrupt truth table.
- 3. Timing depends on which enable signal ($\overline{\text{CE}}$ or $R/\overline{\text{W}}$) is asserted last.
- 4. Timing depends on which enable signal $(\overline{CE} \text{ or } R/\overline{W})$ is de-asserted first.

TRUTH TABLES

TRUTH TABLE I — INTERRUPT FLAG^(1,4)

	Left Port					Right Port				
R ∕W L	CEL	<u>OE</u> L	A14L-A0L	<u>INT</u> L	R/₩R	CER	ŌE R	A14R-A0R	ĪNT R	Function
L	L	Х	7FFF	Χ	Х	Х	Х	Х	L ⁽²⁾	Set Right INTR Flag
Х	Х	Х	Х	Х	Х	L	L	7FFF	H ⁽³⁾	Reset Right INTR Flag
Х	Х	Х	Х	L ⁽³⁾	L	L	Х	7FFE	Х	Set Left INTL Flag
Х	L	L	7FFE	H ⁽²⁾	Х	Х	Х	Х	Х	Reset Left INTL Flag

NOTES:

2739 tbl 16

- 1. Assumes $\overline{BUSY}L = \overline{BUSY}R = VIH$.
- 2. If $\overline{\text{BUSYL}} = \text{VIL}$, then no change.
- 3. If $\overline{BUSYR} = VIL$, then no change.
- 4. INTL and INTR must be initiated at power-up.

TRUTH TABLE II — ADDRESS BUSY ARBITRATION

	Inputs			puts	
CEL	CE R	A0L-A14L A0R-A14R	BUSY _L ⁽¹⁾	BUSYR ⁽¹⁾	Function
Х	Х	NO MATCH	Н	Н	Normal
Н	Х	MATCH	Н	Н	Normal
Х	Н	MATCH	Н	Н	Normal
L	L	MATCH	(2)	(2)	Write Inhibit ⁽³⁾

NOTES:

- 2940 tbl 17
- 1. Pins BUSYL and BUSYR are both outputs when the part is configured as a master. Both are inputs when configured as a slave. BUSY outputs on the IDT7007 are push-pull, not open drain outputs. On slaves the BUSY input internally inhibits writes.
- 2. "L" if the inputs to the opposite port were stable prior to the address and enable inputs of this port. "H" if the inputs to the opposite port became stable after the address and enable inputs of this port. If taps is not met, either BUSYL or BUSYR = LOW will result. BUSYL and BUSYR outputs can not be LOW simultaneously.
- 3. Writes to the left port are internally ignored when BUSYL outputs are driving LOW regardless of actual logic level on the pin. Writes to the right port are internally ignored when BUSYR outputs are driving LOW regardless of actual logic level on the pin.

TRUTH TABLE III — EXAMPLE OF SEMAPHORE PROCUREMENT SEQUENCE(1,2)

Functions	Do - D7 Left	Do - D7 Right	Status
No Action	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Right Port Writes "0" to Semaphore	0	1	No change. Right side has no write access to semaphore
Left Port Writes "1" to Semaphore	1	0	Right port obtains semaphore token
Left Port Writes "0" to Semaphore	1	0	No change. Left port has no write access to semaphore
Right Port Writes "1" to Semaphore	0	1	Left port obtains semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free
Right Port Writes "0" to Semaphore	1	0	Right port has semaphore token
Right Port Writes "1" to Semaphore	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free

NOTES:

2940 tbl 18

- 1. This table denotes a sequence of events for only one of the eight semaphores on the IDT7007.
- 2. There are eight semaphore flags written to via I/Oo and read from all I/O's (I/Oo-I/O7). These eight semaphores are addressed by Ao A2.

FUNCTIONAL DESCRIPTION

The IDT7007 provides two ports with separate control, address and I/O pins that permit independent access for reads or writes to any location in memory. The IDT7007 has an automatic power down feature controlled by $\overline{\text{CE}}$. The $\overline{\text{CE}}$ controls on-chip power down circuitry that permits the respective port to go into a standby mode when not selected ($\overline{\text{CE}}$ HIGH). When a port is enabled, access to the entire memory array is permitted.

INTERRUPTS

If the user chooses to use the interrupt function, a memory location (mail box or message center) is assigned to each port. The left port interrupt flag (\overline{INTL}) is asserted when the right port writes to memory location 7FFE (HEX), where a write is defined as $\overline{CE} = R/\overline{W} = VIL$ per the Truth Table. The left port clears the interrupt through access of address location 7FFE when $\overline{CER} = \overline{OER} = VIL$, R/\overline{W} is a "don't care". Likewise, the right port interrupt flag (\overline{INTR}) is asserted when the left port writes to memory location 7FFF (HEX) and to clear the interrupt flag (\overline{INTR}), the right port must read the memory

location 7FFF. The message (8 bits) at 7FFE or 7FFF is userdefined since it is an addressable SRAM location. If the interrupt function is not used, address locations 7FFE and 7FFF are not used as mail boxes, but as part of the random access memory. Refer to Truth Table for the interrupt operation.

BUSY LOGIC

Busy Logic provides a hardware indication that both ports of the RAM have accessed the same location at the same time. It also allows one of the two accesses to proceed and signals the other side that the RAM is "Busy". The busy pin can then be used to stall the access until the operation on the other side is completed. If a write operation has been attempted from the side that receives a busy indication, the write signal is gated internally to prevent the write from proceeding.

The use of busy logic is not required or desirable for all applications. In some cases it may be useful to logically OR the busy outputs together and use any busy indication as an interrupt source to flag the event of an illegal or illogical

operation. If the write inhibit function of busy logic is not desirable, the busy logic can be disabled by placing the part in slave mode with the M/\overline{S} pin. Once in slave mode the \overline{BUSY} pin operates solely as a write inhibit input pin. Normal operation can be programmed by tying the \overline{BUSY} pins HIGH. If desired, unintended write operations can be prevented to a port by tying the busy pin for that port LOW.

The busy outputs on the IDT 7007 RAM in master mode, are push-pull type outputs and do not require pull up resistors to operate. If these RAMs are being expanded in depth, then the busy indication for the resulting array requires the use of an external AND gate.

WIDTH EXPANSION WITH BUSY LOGIC MASTER/SLAVE ARRAYS

When expanding an IDT7007 RAM array in width while using busy logic, one master part is used to decide which side of the RAMs array will receive a busy indication, and to output that indication. Any number of slaves to be addressed in the same address range as the master, use the busy signal as a

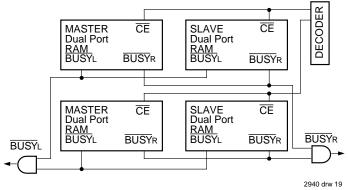


Figure 3. Busy and chip enable routing for both width and depth expansion with IDT7007 RAMs.

write inhibit signal. Thus on the IDT7007 RAM the busy pin is an output if the part is used as a master (M/\overline{S} pin = H), and the busy pin is an input if the part used as a slave (M/\overline{S} pin = L) as shown in Figure 3.

If two or more master parts were used when expanding in width, a split decision could result with one master indicating busy on one side of the array and another master indicating busy on one other side of the array. This would inhibit the write operations from one port for part of a word and inhibit the write operations from the other port for the other part of the word.

The busy arbitration, on a master, is based on the chip enable and address signals only. It ignores whether an access is a read or write. In a master/slave array, both address and chip enable must be valid long enough for a busy flag to be output from the master before the actual write pulse can be initiated with the R/\overline{W} signal. Failure to observe this timing can result in a glitched internal write inhibit signal and corrupted data in the slave.

SEMAPHORES

The IDT7007 is an extremely fast Dual-Port 16K x 8 CMOS Static RAM with an additional 8 address locations dedicated to binary semaphore flags. These flags allow either processor

on the left or right side of the Dual-Port RAM to claim a privilege over the other processor for functions defined by the system designer's software. As an example, the semaphore can be used by one processor to inhibit the other from accessing a portion of the Dual-Port RAM or any other shared resource.

The Dual-Port RAM features a fast access time, and both ports are completely independent of each other. This means that the activity on the left port in no way slows the access time of the right port. Both ports are identical in function to standard CMOS Static RAM and can be read from, or written to, at the same time with the only possible conflict arising from the simultaneous writing of, or a simultaneous READ/WRITE of, a non-semaphore location. Semaphores are protected against such ambiguous situations and may be used by the system program to avoid any conflicts in the non-semaphore portion of the Dual-Port RAM. These devices have an automatic power-down feature controlled by \overline{CE} , the Dual-Port RAM enable, and SEM, the semaphore enable. The CE and SEM pins control on-chip power down circuitry that permits the respective port to go into standby mode when not selected. This is the condition which is shown in Truth Table where CE and SEM are both HIGH.

Systems which can best use the IDT7007 contain multiple processors or controllers and are typically very high-speed systems which are software controlled or software intensive. These systems can benefit from a performance increase offered by the IDT7007s hardware semaphores, which provide a lockout mechanism without requiring complex programming.

Software handshaking between processors offers the maximum in system flexibility by permitting shared resources to be allocated in varying configurations. The IDT7007 does not use its semaphore flags to control any resources through hardware, thus allowing the system designer total flexibility in system architecture.

An advantage of using semaphores rather than the more common methods of hardware arbitration is that wait states are never incurred in either processor. This can prove to be a major advantage in very high-speed systems.

HOW THE SEMAPHORE FLAGS WORK

The semaphore logic is a set of eight latches which are independent of the Dual-Port RAM. These latches can be used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphores provide a hardware assist for a use assignment method called "Token Passing Allocation." In this method, the state of a semaphore latch is used as a token indicating that shared resource is in use. If the left processor wants to use this resource, it requests the token by setting the latch. This processor then verifies its success in setting the latch by reading it. If it was successful, it proceeds to assume control over the shared resource. If it was not successful in setting the latch, it determines that the right side processor has set the latch first, has the token and is using the shared resource. The left processor can then either repeatedly request that semaphore's status or remove its request for that semaphore

to perform another task and occasionally attempt again to gain control of the token via the set and test sequence. Once the right side has relinquished the token, the left side should succeed in gaining control.

The semaphore flags are active LOW. A token is requested by writing a zero into a semaphore latch and is released when the same side writes a one to that latch.

The eight semaphore flags reside within the IDT7007 in a separate memory space from the Dual-Port RAM. This address space is accessed by placing a low input on the SEM pin (which acts as a chip select for the semaphore flags) and using the other control pins (Address, \overline{OE} , and R/W) as they would be used in accessing a standard Static RAM. Each of the flags has a unique address which can be accessed by either side through address pins A0 – A2. When accessing the semaphores, none of the other address pins has any effect.

When writing to a semaphore, only data pin Do is used. If a low level is written into an unused semaphore location, that flag will be set to a zero on that side and a one on the other side (see Table III). That semaphore can now only be modified by the side showing the zero. When a one is written into the same location from the same side, the flag will be set to a one for both sides (unless a semaphore request from the other side is pending) and then can be written to by both sides. The fact that the side which is able to write a zero into a semaphore subsequently locks out writes from the other side is what makes semaphore flags useful in interprocessor communications. (A thorough discussing on the use of this feature follows shortly.) A zero written into the same location from the other side will be stored in the semaphore request latch for that side until the semaphore is freed by the first side.

When a semaphore flag is read, its value is spread into all data bits so that a flag that is a one reads as a one in all data bits and a flag containing a zero reads as all zeros. The read value is latched into one side's output register when that side's semaphore select ($\overline{\text{SEM}}$) and output enable ($\overline{\text{OE}}$) signals go active. This serves to disallow the semaphore from changing state in the middle of a read cycle due to a write cycle from the other side. Because of this latch, a repeated read of a semaphore in a test loop must cause either signal ($\overline{\text{SEM}}$ or $\overline{\text{OE}}$) to go inactive or the output will never change.

A sequence WRITE/READ must be used by the semaphore in order to guarantee that no system level contention will occur. A processor requests access to shared resources by attempting to write a zero into a semaphore location. If the semaphore is already in use, the semaphore request latch will contain a zero, yet the semaphore flag will appear as one, a fact which the processor will verify by the subsequent read (see Table III). As an example, assume a processor writes a zero to the left port at a free semaphore location. On a subsequent read, the processor will verify that it has written successfully to that location and will assume control over the resource in question. Meanwhile, if a processor on the right side attempts to write a zero to the same semaphore flag it will fail, as will be verified by the fact that a one will be read from that semaphore on the right side during subsequent read. Had a sequence of READ/WRITE been used instead, system contention problems could have occurred during the gap between the read and write cycles.

It is important to note that a failed semaphore request must be followed by either repeated reads or by writing a one into the same location. The reason for this is easily understood by looking at the simple logic diagram of the semaphore flag in Figure 4. Two semaphore request latches feed into a semaphore flag. Whichever latch is first to present a zero to the semaphore flag will force its side of the semaphore flag LOW and the other side HIGH. This condition will continue until a one is written to the same semaphore request latch. Should the other side's semaphore request latch have been written to a zero in the meantime, the semaphore flag will flip over to the other side as soon as a one is written into the first side's request latch. The second side's flag will now stay low until its

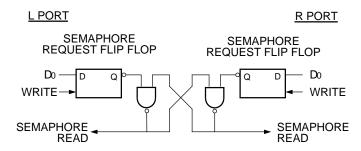


Figure 4. IDT7007 Semaphore Logic

2940 drw 20

semaphore request latch is written to a one. From this it is easy to understand that, if a semaphore is requested and the processor which requested it no longer needs the resource, the entire system can hang up until a one is written into that semaphore request latch.

The critical case of semaphore timing is when both sides request a single token by attempting to write a zero into it at the same time. The semaphore logic is specially designed to resolve this problem. If simultaneous requests are made, the logic guarantees that only one side receives the token. If one side is earlier than the other in making the request, the first side to make the request will receive the token. If both requests arrive at the same time, the assignment will be arbitrarily made to one port or the other.

One caution that should be noted when using semaphores is that semaphores alone do not guarantee that access to a resource is secure. As with any powerful programming technique, if semaphores are misused or misinterpreted, a software error can easily happen.

Initialization of the semaphores is not automatic and must be handled via the initialization program at power-up. Since any semaphore request flag which contains a zero must be reset to a one, all semaphores on both sides should have a one written into them at initialization from both sides to assure that they will be free when needed.

USING SEMAPHORES—SOME EXAMPLES

Perhaps the simplest application of semaphores is their application as resource markers for the IDT7007's Dual-Port RAM. Say the 32K x 8 RAM was to be divided into two 16K x 8 blocks which were to be dedicated at any one time to servicing either the left or right port. Semaphore 0 could be used to indicate the side which would control the lower section

of memory, and Semaphore 1 could be defined as the indicator for the upper section of memory.

To take a resource, in this example the lower 16K of Dual-Port RAM, the processor on the left port could write and then read a zero in to Semaphore 0. If this task were successfully completed (a zero was read back rather than a one), the left processor would assume control of the lower 16K. Meanwhile the right processor was attempting to gain control of the resource after the left processor, it would read back a one in response to the zero it had attempted to write into Semaphore 0. At this point, the software could choose to try and gain control of the second 16K section by writing, then reading a zero into Semaphore 1. If it succeeded in gaining control, it would lock out the left side.

Once the left side was finished with its task, it would write a one to Semaphore 0 and may then try to gain access to Semaphore 1. If Semaphore 1 was still occupied by the right side, the left side could undo its semaphore request and perform other tasks until it was able to write, then read a zero into Semaphore 1. If the right processor performs a similar task with Semaphore 0, this protocol would allow the two processors to swap 16K blocks of Dual-Port RAM with each other.

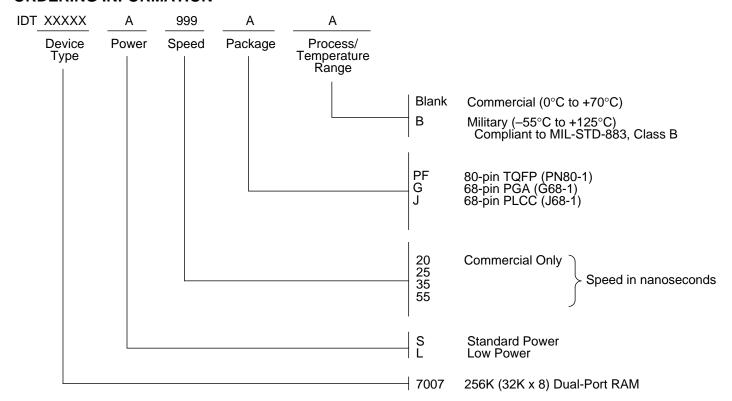
The blocks do not have to be any particular size and can even be variable, depending upon the complexity of the software using the semaphore flags. All eight semaphores could be used to divide the Dual-Port RAM or other shared resources into eight parts. Semaphores can even be assigned different meanings on different sides rather than being given a common meaning as was shown in the example above.

Semaphores are a useful form of arbitration in systems like disk interfaces where the CPU must be locked out of a section of memory during a transfer and the I/O device cannot tolerate any wait states. With the use of semaphores, once the two devices has determined which memory area was "off-limits" to the CPU, both the CPU and the I/O devices could access their assigned portions of memory continuously without any wait states.

Semaphores are also useful in applications where no memory "WAIT" state is available on one or both sides. Once a semaphore handshake has been performed, both processors can access their assigned RAM segments at full speed.

Another application is in the area of complex data structures. In this case, block arbitration is very important. For this application one processor may be responsible for building and updating a data structure. The other processor then reads and interprets that data structure. If the interpreting processor reads an incomplete data structure, a major error condition may exist. Therefore, some sort of arbitration must be used between the two different processors. The building processor arbitrates for the block, locks it and then is able to go in and update the data structure. When the update is completed, the data structure block is released. This allows the interpreting processor to come back and read the complete data structure, thereby guaranteeing a consistent data structure.

ORDERING INFORMATION



2940 drw 21